



# 100% Material Declaration Data Sheet PQG160

PK122 (v1.2.1) October 19, 2006

Material Declaration Data Sheet

**Average Weight: 5.8 g**

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
<b>Silicon Die</b>					<b>0.07366</b>	<b>1.27%</b>
	Silicon	7440-21-3	100.00		0.07366	
<b>Die Attach Material</b>					<b>0.00928</b>	<b>0.16%</b>
	Silver	7440-22-4	78.00		0.0072384	
	Epoxy (EP)	Trade Secret	22.00		0.0020416	
<b>Mold Compound</b>					<b>4.92304</b>	<b>84.88%</b>
	Epoxy Resin (EP)	Trade Secret	9.00		0.4430736	
	Phenolic Resin	Trade Secret	7.00		0.3446128	
	Carbon Black	1333-86-4	0.50		0.0246152	
	Silica	60676-86-0	82.50		4.061508	
	Bismuth	7440-69-9	Max 1.00		0.0492304	
<b>Leadframe</b>					<b>0.73486</b>	<b>12.67%</b>
	Copper	7440-50-8	98.85		0.72640911	
	Chromium	7440-47-3	0.30		0.00220458	
	Tin	7440-31-5	0.25		0.00183715	
	Zinc	7440-66-6	0.60		0.00440916	
<b>Leadframe Plating</b>					<b>0.00638</b>	<b>0.11%</b>
	Silver	7440-22-4	100.00		0.00638	
<b>Bond Wire</b>					<b>0.01392</b>	<b>0.24%</b>
	Gold	7440-57-5	100.00		0.01392	
<b>Ext. Plating</b>					<b>0.03886</b>	<b>0.67 %</b>
	Tin	7440-31-5	100.00		0.03886	

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## Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
3/08/06	1.0	Initial release.
7/05/06	1.1	100% Material Declaration.
9/28/06	1.2	Updated component descriptions.
10/19/06	1.2.1	Editorial change; corrected typo in Substance Description.